

1 2 3 4 5 6 7 8

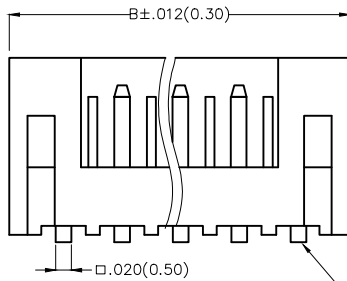
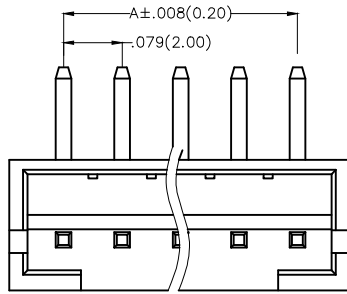
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1	△	Size changes	24/APR/22	MATT	CHERRY
2	△	Flammability Rating change	15/AUG/24	KATE	LEO

Electrical

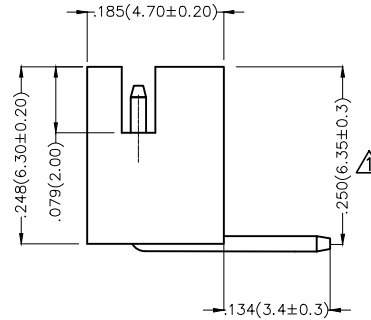
Current Rating: 2.0A AC(rms)/DC
 Voltage Rating: 100V AC(rms)/DC
 Contact Resistance: 10 mΩ Max
 Insulation Resistance: 1000 MΩ MIN
 Withstanding Voltage: 800V AC r.m.s
 Temperature Range-Operating: -25°C~+85°C

Material and Plating

Housing: PA66 (UL 94V-0) △
 Contact Pin: Brass
 Plating: Full gold/ Full tin



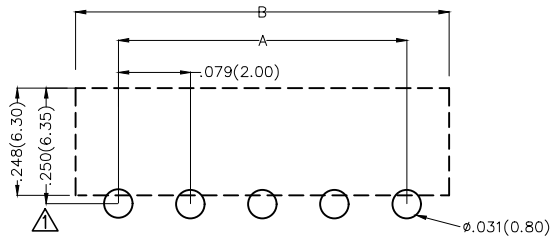
Circuit No.1




Ordering Information

FWF 200 16 — S XX B X 2 W1 B
 1 2 3 4 5 6 7 8 9 10

1 Category FWF-Wafer	2 Series Number 200-Pitch2.0mm	3 Distinction No. 16	4 Row Option S-Single Row	5 Circuits XX	6 Entry Angle B-90° Angle
7 Plating 1-Gold Plated 2-Tin Plated	8 Material-Resin 2-PA66	9 Color-Resin W1-White	10 Packaging B-PE Bag		



Recommended P.C.Board Layout

THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 18/JUN/13	PART NO. FWF20016-SXXBX2W1B	ITEM NO. FWF20016	 Leader Of Industry
	DESIGN UNITS Inch (metric)	X.±.012(0.30) X.X±.008(0.20) X.XX±.006(0.15) X.XXX±.004(0.10)	X'±5' .X'±2' .XX'±1' .XXX'±0.5'	CHECKED BY JACOB	DATE 18/JUN/13	TITLE Wire to Board (Wafer) Pitch 2.0mm 90° Angled (DIP)	
SCALE 5:1	SIZE A4		DRAWN BY CHERRY	DATE 18/JUN/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		REV 2 SHEET NO. 1/2

1 2 3 4 5 6 7 8

1 | 2 | 3 | 4 | 5 | 6 | 7 | 8

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

A

B

C

D

E

F

A

B



C

D

E

F

Circuits (n)	Part No.	Dimensions(in/mm)	
		A	B Δ
2	FWF20016-S02BX2W1B	.079(2.00)	.240(6.10)
3	FWF20016-S03BX2W1B	.157(4.00)	.319(8.10)
4	FWF20016-S04BX2W1B	.236(6.00)	.398(10.10)
5	FWF20016-S05BX2W1B	.315(8.00)	.477(12.10)
6	FWF20016-S06BX2W1B	.394(10.00)	.555(14.10)
7	FWF20016-S07BX2W1B	.472(12.00)	.634(16.10)
8	FWF20016-S08BX2W1B	.551(14.00)	.713(18.10)
9	FWF20016-S09BX2W1B	.630(16.00)	.791(20.10)
10	FWF20016-S10BX2W1B	.709(18.00)	.870(22.10)
11	FWF20016-S11BX2W1B	.787(20.00)	.949(24.10)
12	FWF20016-S12BX2W1B	.866(22.00)	1.028(26.10)
13	FWF20016-S13BX2W1B	.945(24.00)	1.106(28.10)
14	FWF20016-S14BX2W1B	1.024(26.00)	1.185(30.10)
15	FWF20016-S15BX2W1B	1.102(28.00)	1.264(32.10)
16	FWF20016-S16BX2W1B	1.181(30.00)	1.343(34.10)

 THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 18/JUN/13	PART NO. FWF20016-SXXBX2W1B	ITEM NO. FWF20016	 Leader Of Industry	
	DESIGN UNITS Inch (metric)	X.±.012(0.30) X.±5'	CHECKED BY JACOB	DATE 18/JUN/13	TITLE Wire to Board (Wafer) Pitch 2.0mm 90° Anglel (DIP)			REV 2 SHEET NO. 2/2
	SCALE 5:1	SIZE A4	X.XX±.008(0.20) .X'±2'	DRAWN BY CHERRY	DATE 18/JUN/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
			X.XX±.006(0.15) .XX'±1'					
		X.XXX±.004(0.10) .XXX'±0.5'						

1 | 2 | 3 | 4 | 5 | 6 | 7 | 8